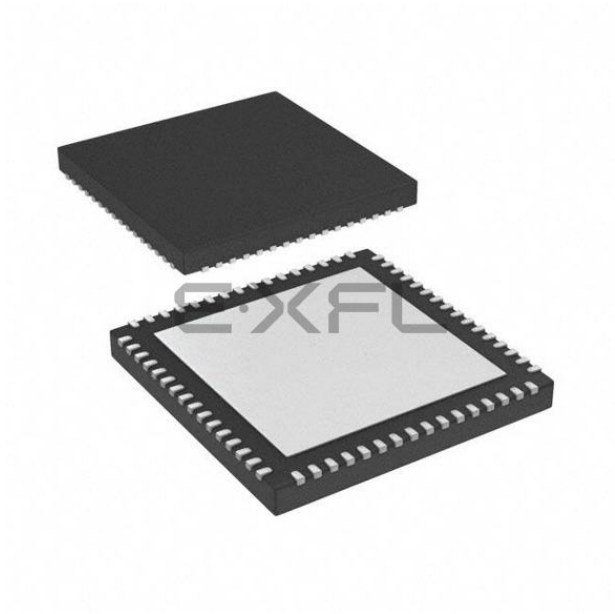

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	53
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx170f512h-i-mr

TABLE 3: PIN NAMES FOR 64-PIN USB DEVICES

64-PIN QFN(4) AND TQFP (TOP VIEW)

PIC32MX230F128H
PIC32MX530F128H
PIC32MX250F256H
PIC32MX550F256H
PIC32MX270F512H
PIC32MX570F512H

64 1

QFN(4)

64 1

TQFP

Pin #	Full Pin Name	Pin #	Full Pin Name
1	AN22/RPE5/PMD5/RE5	33	USBID/RPF3/RF3
2	AN23/PMD6/RE6	34	VBUS
3	AN27/PMD7/RE7	35	VUSB3V3
4	AN16/C1IND/RPG6/SCK2/PMA5/RG6	36	D-
5	AN17/C1INC/RPG7/PMA4/RG7	37	D+
6	AN18/C2IND/RPG8/PMA3/RG8	38	VDD
7	$\overline{\text{MCLR}}$	39	OSC1/CLKI/RC12
8	AN19/C2INC/RPG9/PMA2/RG9	40	OSC2/CLKO/RC15
9	VSS	41	VSS
10	VDD	42	RPD8/RTCC/RD8
11	AN5/C1INA/RPB5/VBUSON/RB5	43	RPD9/SDA1/RD9
12	AN4/C1INB/RB4	44	RPD10/SCL1/PMA15/RD10
13	PGED3/AN3/C2INA/RPB3/RB3	45	RPD11/PMA14/RD11
14	PGEC3/AN2/CTCMP/C2INB/RPB2/CTED13/RB2	46	RPD0/INT0/RD0
15	PGEC1/VREF-/AN1/RPB1/CTED12/RB1	47	SOSCI/RPC13/RC13
16	PGED1/VREF+/AN0/RPB0/PMA6/RB0	48	SOSCO/RPC14/T1CK/RC14
17	PGEC2/AN6/RPB6/RB6	49	AN24/RPD1/RD1
18	PGED2/AN7/RPB7/CTED3/RB7	50	AN25/RPD2/SCK1/RD2
19	AVDD	51	AN26/C3IND/RPD3/RD3
20	AVSS	52	RPD4/PMWR/RD4
21	AN8/RPB8/CTED10/RB8	53	RPD5/PMRD/RD5
22	AN9/RPB9/CTED4/PMA7/RB9	54	C3INC/RD6
23	TMS/CVREFOUT/AN10/RPB10/CTED11/PMA13/RB10	55	C3INB/RD7
24	TDO/AN11/PMA12/RB11	56	VCAP
25	VSS	57	VDD
26	VDD	58	C3INA/RPF0/RF0
27	TCK/AN12/PMA11/RB12	59	RPF1/RF1
28	TDI/AN13/PMA10/RB13	60	PMD0/RE0
29	AN14/RPB14/SCK3/CTED5/PMA1/RB14	61	PMD1/RE1
30	AN15/RPB15/OCFB/CTED6/PMA0/RB15	62	AN20/PMD2/RE2
31	RPF4/SDA2/PMA9/RF4	63	RPE3/CTPLS/PMD3/RE3
32	RPF5/SCL2/PMA8/RF5	64	AN21/PMD4/RE4

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RBx-RGx) can be used as a change notification pin (CNBx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: Shaded pins are 5V tolerant.

4: The metal plane at the bottom of the QFN device is not connected to any pins and is recommended to be connected to VSS externally.

TABLE 4: PIN NAMES FOR 100-PIN GENERAL PURPOSE DEVICES (CONTINUED)

100-PIN TQFP (TOP VIEW)

PIC32MX130F128L
PIC32MX150F256L
PIC32MX170F512L

100

1

Pin #	Full Pin Name	Pin #	Full Pin Name
71	RPD11/PMA14/RD11	86	VDD
72	RPD0/RD0	87	AN44/C3INA/RPF0/PMD11/RF0
73	SOSCI/RPC13/RC13	88	AN45/RPF1/PMD10/RF1
74	SOSCO/RPC14/T1CK/RC14	89	RPG1/PMD9/RG1
75	VSS	90	RPG0/PMD8/RG0
76	AN24/RPD1/RD1	91	RA6
77	AN25/RPD2/RD2	92	CTED8/RA7
78	AN26/C3IND/RPD3/RD3	93	AN46/PMD0/RE0
79	AN40/RPD12/PMD12/RD12	94	AN47/PMD1/RE1
80	AN41/PMD13/RD13	95	RG14
81	RPD4/PMWR/RD4	96	RG12
82	RPD5/PMRD/RD5	97	RG13
83	AN42/C3INC/PMD14/RD6	98	AN20/PMD2/RE2
84	AN43/C3INB/PMD15/RD7	99	RPE3/CTPLS/PMD3/RE3
85	VCAP	100	AN21/PMD4/RE4

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RGx) can be used as a change notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: Shaded pins are 5V tolerant.

TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name	Pin Number		Pin Type	Buffer Type	Description
	64-pin QFN/ TQFP	100-pin TQFP			
AN0	16	25	I	Analog	Analog input channels.
AN1	15	24	I	Analog	
AN2	14	23	I	Analog	
AN3	13	22	I	Analog	
AN4	12	21	I	Analog	
AN5	11	20	I	Analog	
AN6	17	26	I	Analog	
AN7	18	27	I	Analog	
AN8	21	32	I	Analog	
AN9	22	33	I	Analog	
AN10	23	34	I	Analog	
AN11	24	35	I	Analog	
AN12	27	41	I	Analog	
AN13	28	42	I	Analog	
AN14	29	43	I	Analog	
AN15	30	44	I	Analog	
AN16	4	10	I	Analog	
AN17	5	11	I	Analog	
AN18	6	12	I	Analog	
AN19	8	14	I	Analog	
AN20	62	98	I	Analog	
AN21	64	100	I	Analog	
AN22	1	3	I	Analog	
AN23	2	4	I	Analog	
AN24	49	76	I	Analog	
AN25	50	77	I	Analog	
AN26	51	78	I	Analog	
AN27	3	5	I	Analog	
AN28	—	1	I	Analog	
AN29	—	6	I	Analog	
AN30	—	7	I	Analog	
AN31	—	8	I	Analog	
AN32	—	18	I	Analog	
AN33	—	19	I	Analog	
AN34	—	39	I	Analog	
AN35	—	40	I	Analog	

Legend: CMOS = CMOS compatible input or output Analog = Analog input I = Input O = Output
ST = Schmitt Trigger input with CMOS levels TTL = TTL input buffer P = Power

Note 1: This pin is only available on devices without a USB module.

2: This pin is only available on devices with a USB module.

3: This pin is not available on 64-pin devices with a USB module.

4: This pin is only available on 100-pin devices without a USB module.

2.0 GUIDELINES FOR GETTING STARTED WITH 32-BIT MCUS

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX/5XX 64/100-pin family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2.1 Basic Connection Requirements

Getting started with the PIC32MX1XX/2XX/5XX 64/100-pin family of 32-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins, even if the ADC module is not used (see **2.2 "Decoupling Capacitors"**)
- VCAP pin (see **2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**)
- $\overline{\text{MCLR}}$ pin (see **2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins, used for In-Circuit Serial Programming (ICSP™) and debugging purposes (see **2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins, when external oscillator source is used (see **2.7 "External Oscillator Pins"**)

The following pins may be required:

VREF+/VREF- pins, used when external voltage reference for the ADC module is implemented.

Note: The AVDD and AVSS pins must be connected, regardless of ADC use and the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on power supply pins, such as VDD, VSS, AVDD and AVSS is required. See Figure 2-1.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A value of 0.1 µF (100 nF), 10-20V is recommended. The capacitor should be a low Equivalent Series Resistance (low-ESR) capacitor and have resonance frequency in the range of 20 MHz and higher. It is further recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended that the capacitors be placed on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input voltage low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB REAL ICE™.

For more information on MPLAB ICD 3 and MPLAB REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- *"Using MPLAB® ICD 3"* (poster) DS50001765
- *"MPLAB® ICD 3 Design Advisory"* DS50001764
- *"MPLAB® REAL ICE™ In-Circuit Debugger User's Guide"* DS50001616
- *"Using MPLAB® REAL ICE™ Emulator"* (poster) DS50001749

2.6 JTAG

The TMS, TDO, TDI and TCK pins are used for testing and debugging according to the Joint Test Action Group (JTAG) standard. It is recommended to keep the trace length between the JTAG connector and the JTAG pins on the device as short as possible. If the JTAG connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the TMS, TDO, TDI and TCK pins are not recommended as they will interfere with the programmer or debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input voltage low (V_{IL}) requirements

2.7 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is illustrated in Figure 2-3.

FIGURE 2-3: SUGGESTED OSCILLATOR CIRCUIT PLACEMENT

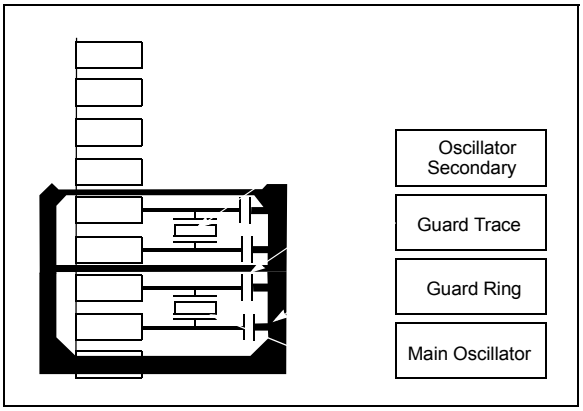


TABLE 4-1: SFR MEMORY MAP

Peripheral	Virtual Address	
	Base	Offset Start
Interrupt Controller	0xBF88	0x1000
Bus Matrix		0x2000
DMA		0x3000
USB		0x5000
PORTA-PORTG		0x6000
CAN1		0xB000
Watchdog Timer	0xBF80	0x0000
RTCC		0x0200
Timer1-Timer5		0x0600
IC1-IC5		0x2000
OC1-OC5		0x3000
I2C1-I2C2		0x5000
SPI1-SPI4		0x5800
UART1-UART5		0x6000
PMP		0x7000
ADC1		0x9000
DAC		0x9800
Comparator 1, 2, 3		0xA000
Oscillator		0xF000
Device and Revision ID		0xF200
Flash Controller		0xF400
PPS		0xFA00
Configuration	0xBFC0	0x0BF0

4.3 Control Registers

Register 4-1 through Register 4-8 are used for setting the RAM and Flash memory partitions for data and code.

REGISTER 4-1: BMXCON: BUS MATRIX CONFIGURATION REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
	—	—	—	BMX ERRIXI	BMX ERRICD	BMX ERRDMA	BMX ERRDS	BMX ERRIS
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	R/W-1	U-0	U-0	U-0	R/W-0	R/W-0	R/W-1
	—	BMX WSDRM	—	—	—	BMXARB<2:0>		

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared

bit 31-21 **Unimplemented:** Read as '0'

bit 20 **BMXERRIXI:** Enable Bus Error from IXI bit
1 = Enable bus error exceptions for unmapped address accesses initiated from IXI shared bus
0 = Disable bus error exceptions for unmapped address accesses initiated from IXI shared bus

bit 19 **BMXERRICD:** Enable Bus Error from ICD Debug Unit bit
1 = Enable bus error exceptions for unmapped address accesses initiated from ICD
0 = Disable bus error exceptions for unmapped address accesses initiated from ICD

bit 18 **BMXERRDMA:** Bus Error from DMA bit
1 = Enable bus error exceptions for unmapped address accesses initiated from DMA
0 = Disable bus error exceptions for unmapped address accesses initiated from DMA

bit 17 **BMXERRDS:** Bus Error from CPU Data Access bit (disabled in Debug mode)
1 = Enable bus error exceptions for unmapped address accesses initiated from CPU data access
0 = Disable bus error exceptions for unmapped address accesses initiated from CPU data access

bit 16 **BMXERRIS:** Bus Error from CPU Instruction Access bit (disabled in Debug mode)
1 = Enable bus error exceptions for unmapped address accesses initiated from CPU instruction access
0 = Disable bus error exceptions for unmapped address accesses initiated from CPU instruction access

bit 15-7 **Unimplemented:** Read as '0'

bit 6 **BMXWSDRM:** CPU Instruction or Data Access from Data RAM Wait State bit
1 = Data RAM accesses from CPU have one wait state for address setup
0 = Data RAM accesses from CPU have zero wait states for address setup

bit 5-3 **Unimplemented:** Read as '0'

bit 2-0 **BMXARB<2:0>:** Bus Matrix Arbitration Mode bits
111 = Reserved (using these configuration modes will produce undefined behavior)
•
•
•
011 = Reserved (using these configuration modes will produce undefined behavior)
010 = Arbitration Mode 2
001 = Arbitration Mode 1 (default)
000 = Arbitration Mode 0

REGISTER 4-2: BMXDKPBA: DATA RAM KERNEL PROGRAM BASE ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0
	BMXDKPBA<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	BMXDKPBA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-10 **BMXDKPBA<15:10>:** DRM Kernel Program Base Address bits
When non-zero, this value selects the relative base address for kernel program space in RAM

bit 9-0 **BMXDKPBA<9:0>:** Read-Only bits
Value is always '0', which forces 1 KB increments

Note 1: At Reset, the value in this register is forced to zero, which causes all of the RAM to be allocated to Kernel mode data usage.

2: The value in this register must be less than or equal to BMXDRMSZ.

9.1 Control Registers

TABLE 9-1: DMA GLOBAL REGISTER MAP

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3000	DMACON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	—	SUSPEND	DMABUSY	—	—	—	—	—	—	—	—	—	—	—	0000
3010	DMASTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RDWR	DMACH<2:0>			0000
3020	DMAADDR	31:16	DMAADDR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET, and INV Registers"** for more information.

TABLE 9-2: DMA CRC REGISTER MAP

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3030	DCRCCON	31:16	—	—	BYTO<1:0>		WBO	—	—	BITO	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	PLEN<4:0>					CRCEN	CRCAPP	CRCTYP	—	—	CRCCH<2:0>			0000
3040	DCRCDATA	31:16	DCRCDATA<31:0>																0000
		15:0																	0000
3050	DCRCXOR	31:16	DCRCXOR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET, and INV Registers"** for more information.

REGISTER 10-8: U1EIR: USB ERROR INTERRUPT STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS
	BTSEF	BMXEF	DMAEF(1)	BTOEF(2)	DFN8EF	CRC16EF	CRC5EF(4) / EOFEF(3,5)	PIDEF

Legend:	WC = Write ‘1’ to clear	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as ‘0’

bit 7 **BTSEF:** Bit Stuff Error Flag bit
- 1 = Packet rejected due to bit stuff error
- 0 = Packet accepted

bit 6 **BMXEF:** Bus Matrix Error Flag bit
- 1 = The base address, of the BDT, or the address of an individual buffer pointed to by a BDT entry, is invalid.
- 0 = No address error

bit 5 **DMAEF:** DMA Error Flag bit(1)
- 1 = USB DMA error condition detected
- 0 = No DMA error

bit 4 **BTOEF:** Bus Turnaround Time-Out Error Flag bit(2)
- 1 = Bus turnaround time-out has occurred
- 0 = No bus turnaround time-out

bit 3 **DFN8EF:** Data Field Size Error Flag bit
- 1 = Data field received is not an integral number of bytes
- 0 = Data field received is an integral number of bytes

bit 2 **CRC16EF:** CRC16 Failure Flag bit
- 1 = Data packet rejected due to CRC16 error
- 0 = Data packet accepted

Note 1: This type of error occurs when the module’s request for the DMA bus is not granted in time to service the module’s demand for memory, resulting in an overflow or underflow condition, and/or the allocated buffer size is not sufficient to store the received data packet causing it to be truncated.

2: This type of error occurs when more than 16-bit-times of Idle from the previous End-of-Packet (EOP) has elapsed.

3: This type of error occurs when the module is transmitting or receiving data and the SOF counter has reached zero.

4: Device mode.

5: Host mode.

REGISTER 18-2: I2CxSTAT: I^{2}C STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R-0, HSC	R-0, HSC	U-0	U-0	U-0	R/C-0, HS	R-0, HSC	R-0, HSC
	ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10
7:0	R/C-0, HS	R/C-0, HS	R-0, HSC	R/C-0, HSC	R/C-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC
	IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF

Legend:	HS = Set in hardware	HSC = Hardware set/cleared	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	C = Clearable bit

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ACKSTAT:** Acknowledge Status bit
(when operating as I^{2}C master, applicable to master transmit operation)
1 = Acknowledge was not received from slave
0 = Acknowledge was received from slave
Hardware set or clear at end of slave Acknowledge.

bit 14 **TRSTAT:** Transmit Status bit (when operating as I^{2}C master, applicable to master transmit operation)
1 = Master transmit is in progress (8 bits + ACK)
0 = Master transmit is not in progress
Hardware set at beginning of master transmission. Hardware clear at end of slave Acknowledge.

bit 13-11 **Unimplemented:** Read as '0'

bit 10 **BCL:** Master Bus Collision Detect bit
1 = A bus collision has been detected during a master operation
0 = No collision
Hardware set at detection of bus collision. This condition can only be cleared by disabling (ON bit = 0) and re-enabling (ON bit = 1) the module.

bit 9 **GCSTAT:** General Call Status bit
1 = General call address was received
0 = General call address was not received
Hardware set when address matches general call address. Hardware clear at Stop detection.

bit 8 **ADD10:** 10-bit Address Status bit
1 = 10-bit address was matched
0 = 10-bit address was not matched
Hardware set at match of 2nd byte of matched 10-bit address. Hardware clear at Stop detection.

bit 7 **IWCOL:** Write Collision Detect bit
1 = An attempt to write the I2CxTRN register failed because the I^{2}C module is busy
0 = No collision
Hardware set at occurrence of write to I2CxTRN while busy (cleared by software).

bit 6 **I2COV:** Receive Overflow Flag bit
1 = A byte was received while the I2CxRCV register is still holding the previous byte
0 = No overflow
Hardware set at attempt to transfer I2CxRSR to I2CxRCV (cleared by software).

bit 5 **D_A:** Data/Address bit (when operating as I^{2}C slave)
1 = Indicates that the last byte received was data
0 = Indicates that the last byte received was device address
Hardware clear at device address match. Hardware set by reception of slave byte.

28.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX/5XX 64/100-pin family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 9. "Watchdog Timer and Power-up Timer"** (DS60001114), **Section 32. "Configuration"** (DS60001124) and **Section 33. "Programming and Diagnostics"** (DS60001129) in the *"PIC32 Family Reference Manual"*, which are available from the Microchip web site (www.microchip.com/PIC32).

PIC32MX1XX/2XX/5XX 64/100-pin devices include several features intended to maximize application flexibility and reliability and minimize cost through elimination of external components. These are:

- Flexible device configuration
- Watchdog Timer (WDT)
- Joint Test Action Group (JTAG) interface
- In-Circuit Serial Programming™ (ICSP™)

28.1 Configuration Bits

The Configuration bits can be programmed using the following registers to select various device configurations.

- DEVCFG0: Device Configuration Word 0
- DEVCFG1: Device Configuration Word 1
- DEVCFG2: Device Configuration Word 2
- DEVCFG3: Device Configuration Word 3
- CFGCON: Configuration Control Register

In addition, the DEVID register (Register 28-6) provides device and revision information.

TABLE 31-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
Param. No.	**Typical(2)**	**Max.**	**Units**	**Conditions**	
Power-Down Current (IPD) (Notes 1, 5)					
DC40k	33	78	μA	-40°C	Base Power-Down Current
DC40l	49	78	μA	+25°C	
DC40n	281	450	μA	+85°C	
DC40m	559	895	μA	+105ºC	
Module Differential Current					
DC41e	10	25	μA	3.6V	Watchdog Timer Current: ΔIWDT **(Note 3)**
DC42e	29	50	μA	3.6V	RTCC + Timer1 w/32 kHz Crystal: ΔIRTCC **(Note 3)**
DC43d	1000	1300	μA	3.6V	ADC: ΔIADC **(Notes 3,4)**

Note 1: The test conditions for IPD current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is set
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD
- RTCC and JTAG are disabled

2: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

5: IPD electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

TABLE 31-31: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS (CONTINUED)

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SP51	TSSH2DOZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance **(Note 4)**	5	—	25	ns	—
SP52	TSCH2SSH TSCL2SSH	$\overline{SSx}$ ↑ after SCKx Edge	TSCK + 20	—	—	ns	—
SP60	TSSL2DOV	SDOx Data Output Valid after $\overline{SSx}$ Edge	—	—	25	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 50 ns.

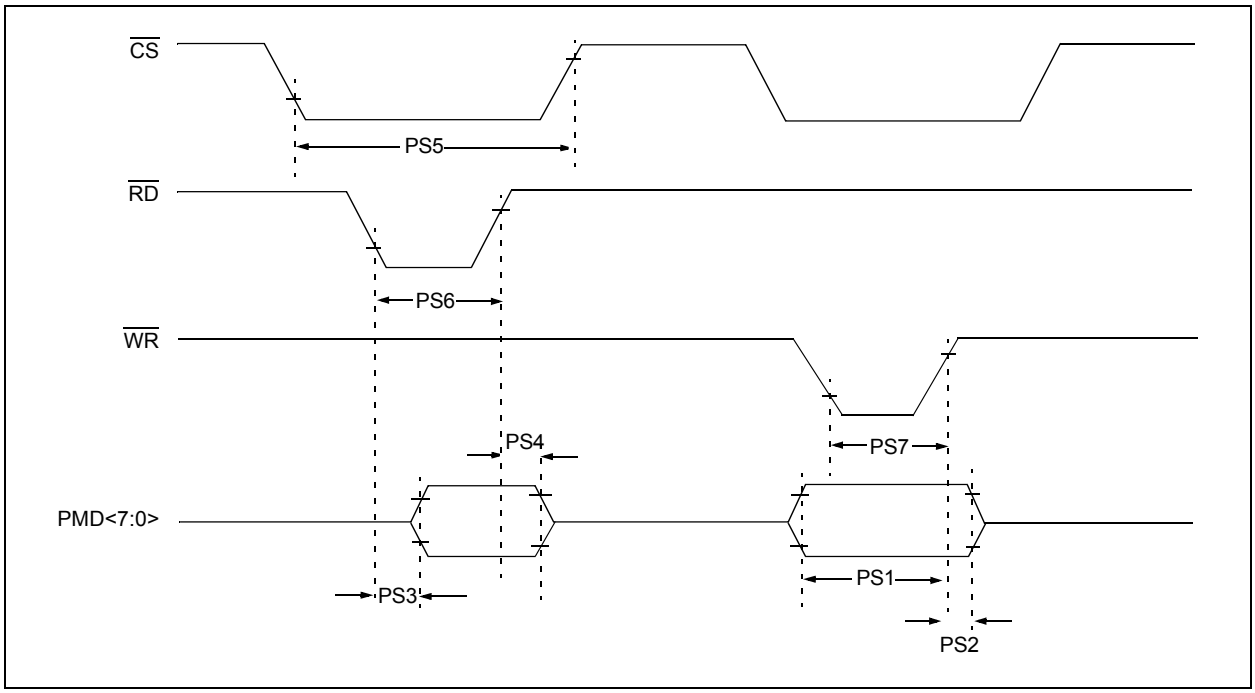
4: Assumes 50 pF load on all SPIx pins.

TABLE 31-33: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE) (CONTINUED)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.**	**Max.**	**Units**	**Conditions**
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	ns	—
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	250		ns	
IS40	TAA:SCL	Output Valid from Clock	100 kHz mode	0	3500	ns	—
			400 kHz mode	0	1000	ns	
			1 MHz mode **(Note 1)**	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	The amount of time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode **(Note 1)**	0.5	—	µs	
IS50	CB	Bus Capacitive Loading		—	400	pF	—

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

FIGURE 31-20: PARALLEL SLAVE PORT TIMING



32.1 DC Characteristics

TABLE 32-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)(1)	Temp. Range (in °C)	Max. Frequency
			PIC32MX1XX/2XX/5XX 64/100-pin Family
MDC5	VBOR-3.6V	-40°C to +85°C	50 MHz

Note 1: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 31-10 for BOR values.

TABLE 32-2: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial	
Parameter No.	Typical(3)	Max.	Units	Conditions
Operating Current (IDD) (Note 1, 2)				
MDC24	25	40	mA	50 MHz

Note 1: A device's IDD supply current is mainly a function of the operating voltage and frequency. Other factors, such as PBCLK (Peripheral Bus Clock) frequency, number of peripheral modules enabled, internal code execution pattern, execution from Program Flash memory vs. SRAM, I/O pin loading and switching rate, oscillator type, as well as temperature, can have an impact on the current consumption.

2: The test conditions for IDD measurements are as follows:

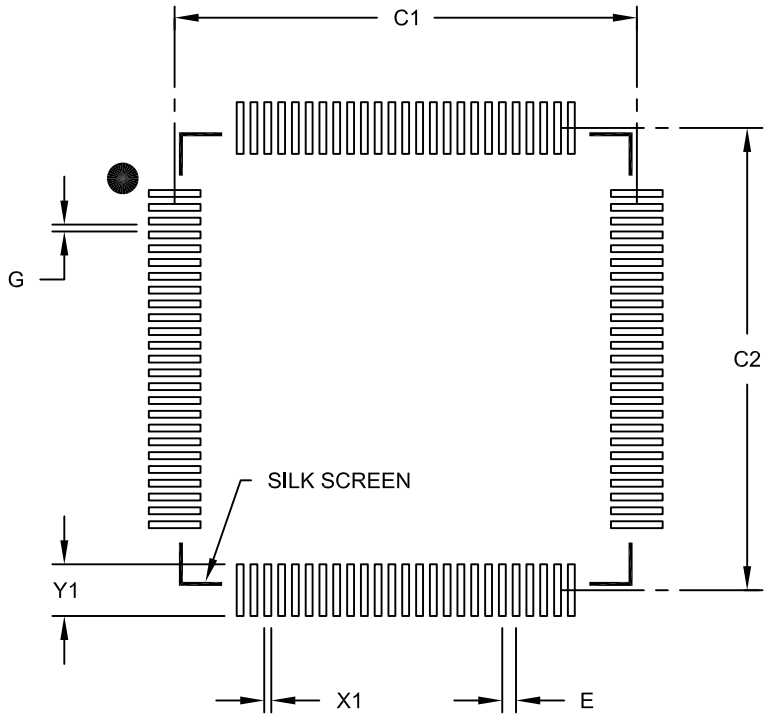
- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU, Program Flash, and SRAM data memory are operational, SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is cleared
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD
- CPU executing `while(1)` statement from Flash

3: RTCC and JTAG are disabled

4: Data in "Typical" column is at 3.3V, 25°C at specified operating frequency unless otherwise stated. Parameters are for design guidance only and are not tested.

100-Lead Plastic Thin Quad Flatpack (PT)-12x12x1mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Contact Pad Spacing	C1		13.40	
Contact Pad Spacing	C2		13.40	
Contact Pad Width (X100)	X1			0.20
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2100B

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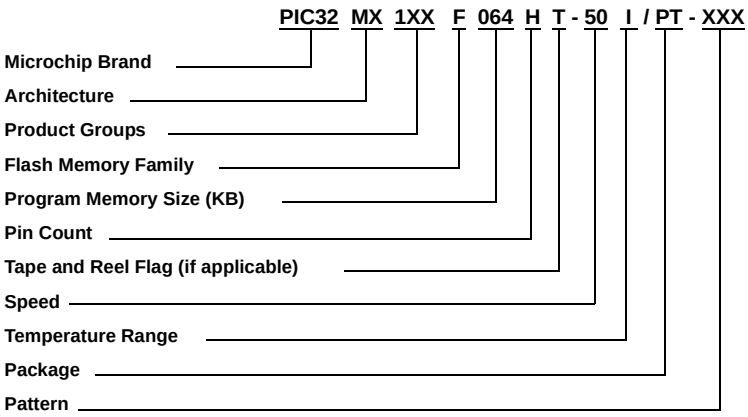
PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Example:

PIC32MX170F512H-50I/PT:
General Purpose PIC32, 32-bit RISC MCU,
512 KB program memory,
64-pin, Industrial temperature,
TQFP package.

Flash Memory Family

Architecture	MX = 32-bit RISC MCU core
Product Groups	1XX = General Purpose microcontroller family 2XX = USB microcontroller family 5XX = USB and CAN microcontroller family
Flash Memory Family	F = Flash program memory
Program Memory Size	064 = 64 KB 128 = 128 KB 256 = 256 KB 512 = 512 KB
Pin Count	H = 64-pin L = 100-pin
Speed	= 40 MHz (blank, no marking on package) 50 = 50 MHz
Temperature Range	I = -40°C to +85°C (Industrial) V = -40°C to +105°C (V-Temp)
Package	PT = 64-Lead (10x10x1 mm) TQFP (Thin Quad Flatpack) PT = 100-Lead (12x12x1 mm) TQFP (Thin Quad Flatpack) PF = 100-Lead (14x14x1 mm) TQFP (Thin Quad Flatpack) MR = 64-Lead (9x9x0.9 mm) QFN (Plastic Quad Flat)
Pattern	Three-digit QTP, SQTP, Code or Special Requirements (blank otherwise) ES = Engineering Sample